V1.1



# N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

## **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent Rds(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

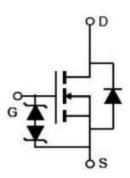
#### **Features**

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V <sub>DS min@Tjmax</sub>	650	V
R <sub>DS(ON)TYP</sub> .	230	mΩ
$I_D$	14	Α
Qg	19	nC



## Schematic diagram

♦ Intrinsic fast-recovery body diode

**Package Marking And Ordering Information** 

Device	Device Package	Marking	
NCE60NF260I	TO-251-3L	NCE60NF260I	



TO-251

## Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> =0V)	V <sub>DS</sub>	600	V
Gate-Source Voltage (V <sub>DS=0</sub> V) ,AC (f>1 Hz)	V <sub>G</sub> s	±30	V
Gate-Source Voltage (V <sub>DS=0</sub> V) ,DC	V <sub>G</sub> s	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	14	A
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	9.8	A
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	42	A
Maximum Power Dissipation(Tc=25℃)	P <sub>D</sub>	128	W
Derate above 25°C		0.85	W/°C
Single pulse avalanche current (Note 2)	I <sub>AS</sub>	2.5	А
Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	50	V/ns
Drain Source voltage slope,V <sub>DS</sub> ≤480 V	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55+175	°C



**Table 2. Thermal Characteristic** 

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	1.17	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

 Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250uA	600			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V			300	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±200	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250uA$	3.4	4.2	5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =7A		230	260	mΩ
Dynamic Characteristics						
Gate Resistance	Rg	F=1MHZ, D-S short		17.3		Ω
Input Capacitance	C <sub>lss</sub>	V 50VV 0V		946		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V,		50		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1MHz		1.6		pF
Total Gate Charge	Qg			19	22	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}\!\!=\!\!400V,I_{D}\!\!=\!\!7A,$		9.8		nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V		3.1		nC
Gate plateau voltage	Vgp			6.8		V
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			18		nS
Turn-on Rise Time	tr	$V_{DD} = 380V, I_D = 7A,$		13		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G$ =4 $\Omega$ , $V_{GS}$ =10 $V$		52		nS
Turn-Off Fall Time	t <sub>f</sub>			10		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T 05°0			14	Α
Pulsed-Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			42	Α
Forward on voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =14A,V <sub>GS</sub> =0V		1.0	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			85		nS
Reverse Recovery Charge	Q <sub>rr</sub>	Tj=25°C,I <sub>F=</sub> 7A,		0.29		uC
Peak reverse recovery current	I <sub>rrm</sub>	di/dt=100A/µs		7		Α

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^{\circ}\text{C}$  ,VDD=50V,VG=10V, RG=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

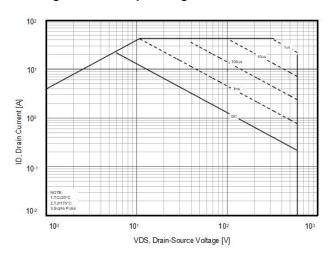


Figure 2. Source-Drain Diode Forward Voltage

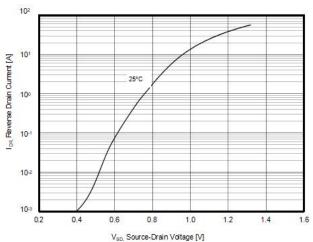


Figure 3. Transfer characteristics

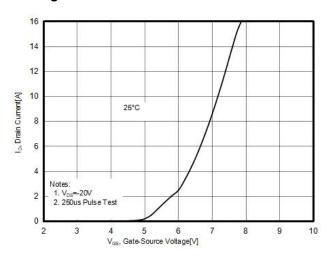


Figure 4. Output characteristics

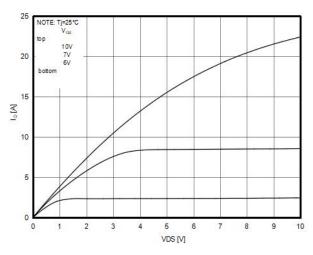


Figure 5. Static drain-source on resistance

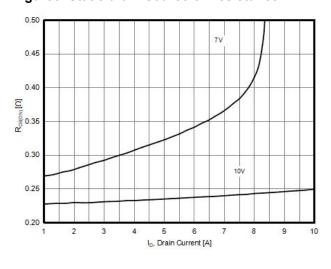
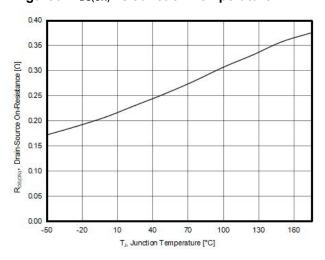


Figure 6. RDS(ON) vs Junction Temperature



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Figure 7. BV<sub>DSS</sub> vs Junction Temperature

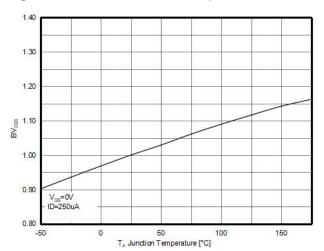


Figure 8. Maximum ID vs Junction Temperature

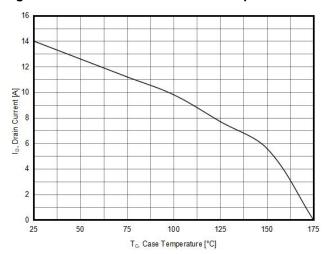


Figure 9. Gate charge waveforms

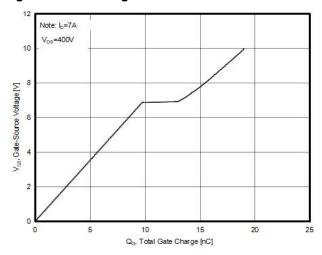
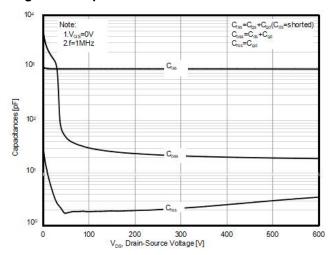


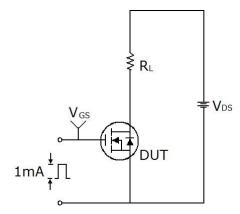
Figure 10. Capacitance

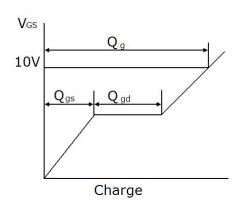




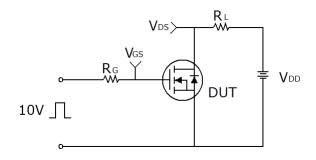
## **Test circuit**

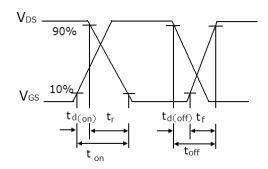
## 1) Gate charge test circuit & Waveform



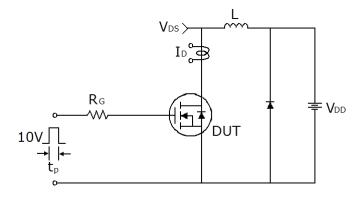


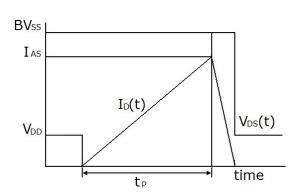
## 2) Switch Time Test Circuit:





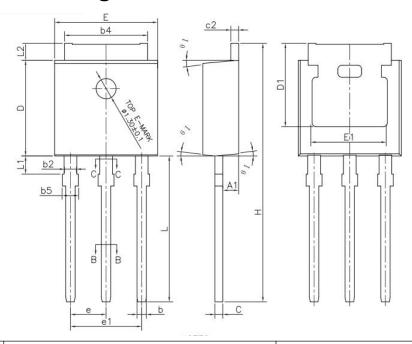
## 3) Unclamped Inductive Switching Test Circuit & Waveforms







# **TO-251-3L-P Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.20	2.35	0.087	0.093	
A1	0.90	1.10	0.035	0.043	
b	0.56	0.69	0.022	0.027	
b1	0.55	0.65	0.022	0.026	
b2	0.77	0.90	0.030	0.035	
b3	0.76	0.86	0.030	0.034	
b4	5.23	5.43	0.206	0.214	
b5		1.05		0.041	
С	0.46	0.59	0.018	0.023	
c1	0.45	0.55	0.018	0.022	
c2	0.46	0.59	0.018	0.023	
D	6.00	6.20	0.236	0.244	
D1	5.20		0.205		
Е	6.50	6.70	0.256	0.264	
E1	4.60	5.00	0.181	0.197	
е	2.24	2.34	0.088	0.092	
e1	4.47	4.67	0.176	0.184	
Н	16.18	16.78	0.637	0.661	
L	9.00	9.60	0.354	0.378	
L1	0.95	1.35	0.037	0.053	
L2	0.90	1.25	0.035	0.049	



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